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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES

In re application of

AMITABH JAIN ET AL.

Serial No. 10/816,776 (TI-34913AA)

Filed April 2, 2004

For: ULTRA SHALLOW JUNCTION
FORMATION

Art Unit 2813

Examiner David S. Blum

Customer No. 23494

Mail Stop Appeal Brief-Patents
Commissioner for Patents
P. O. Box 1450
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Sir:

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SUPPLEMENTAL REPLY BRIEF

In reply to the Supplemental Examiner's Answer, it is again noted that the invention relates to a method for forming ultra shallow junctions in a semiconductor substrate whereas this is not the purpose of Mayur and it therefore follows that, for this reason alone, any attempt to stretch the ranges of Mayur to equate them to those claimed is improper and merely a result of an

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